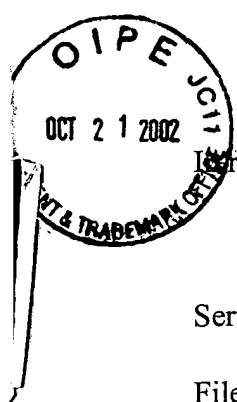


2825

#7/B  
10/30/02



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:  
Shubneesh Batra et al.

Serial No.: 09/901,837

Filed: July 10, 2001

For: LOW TEMPERATURE REFLOW  
METHOD FOR FILLING HIGH  
ASPECT RATIO CONTACTS

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Group Art Unit: 2825

Examiner: Everhart, C.

Atty Docket: MCRO:199--3/FLE  
95-0057.03

Assistant Commissioner  
for Patents  
Washington, D.C. 20231

CERTIFICATE OF MAILING 37 C.F.R. 1.8	
I hereby certify that this correspondence is being deposited with the U.S. Postal Service as First Class Mail in an envelope addressed to: Assistant Commissioner for Patents, Washington, D.C. 20231, on the date below:	
October 15, 2002 Date	 Helen Tinsley

Sir:

AMENDMENT AND RESPONSE

Please amend the above-identified application, as follows:

IN THE CLAIMS

Please cancel claims 36, 45, 57 and 63, without prejudice.

Please amend claims 1, 30, 40, 48 and 60, as follows:

1 (Once Amended). A method of processing a semiconductor substrate, comprising the steps of:

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